

HUAWEI franchise expands 3G and 4G cellular M2M communications portfolio at SILICA

Poing, Germany, 25th February 2015 – SILICA, an [Avnet](#), Inc. (NYSE: [AVT](#)) company, has announced a franchise agreement with Huawei, the worldwide leading global vendor of cellular wireless infrastructure and modules. Under the agreement, SILICA is marketing multi-standard 3G and 4G wireless modules in a choice of popular form factors, including LGA, PCIe and PCI-SIG M.2. Based on HUAWEI HiSilicon chipset technology, the new modules offer features specific for M2M communication. As a leading distributor, SILICA provides in-depth technical support and is providing software support out of the box for HUAWEI modules for their ArchiTech evaluation boards, accelerating and facilitating the product development.

M2M communications and wider Internet of Things (IoT) applications demand low power, high reliability wireless links. Where cellular radio networks are employed, certified products that support multiple standards and operators are preferred, allowing for networks updates and minimizing inventory if the same products are to be used in more than one country. HUAWEI modules support over 90% of operators worldwide.

Even though lower data rates may be adequate for many of today's M2M applications, 3G (HSPA/HSPA+) is now becoming the dominant standard and 4G (LTE/LTE-A) networks are being rolled out rapidly. As a result, designers need to specify 3G or dual-standard 3G/4G modules to ensure that products have a long operating life.

Latest product released by Huawei is MU709, first industrial module based on company's in-house HiSilicon chipset Balong 330.

MU709s is a HSPA+ M2M module that is available in two different versions: Dual-band for the European market und Tri-band for the Latin-American market. It supports data

speed up to 21.6 Mbps in downlink and up to 5.76 Mbps in uplink. In addition, both versions support Quad-band EDGE/GPRS/GSM as well as various features as HTTP, FTP, FOTA, Jamming Detection, Netscan, Cell lock, CMUX and eCall. The new module comes in a compact form factor of 30mm x 30mm x 2.3mm and 146 pin LGA package. Thus it is pin compatible with the entire LGA product family of Huawei MU509, MC509, MU609 and ME909, which makes migration from one technology to another much easier. Additionally the MU709s is also available with miniPCIE interface.

This module is the first model of a new generation of products based on HiSilicon chipsets, providing excellent RF performance and extended features set for M2M Market.

Georg Steimel, head of M2M Solutions, HUAWEI, said, “We are very glad to have found an experienced franchise partner with SILICA that will enable us to significantly leverage the marketing of our products. Its outstanding expertise in the industry and in-depth support make SILICA an ideal partner. The partnership with the agile and market leading player will accelerate our growth significantly and in combination with our innovative technology will help to gain the leadership in this market.”

Mario Orlandi, president SILICA, commented, “The SILICA team is fully engaged around the many opportunities that come when working with the world’s leading cellular communications company. The rate of innovation at Huawei is exceptional and will ensure that we’re able to provide our customers with leading-edge products in terms of performance, cost-effectiveness and reliability. M2M and the general IoT market is the fastest growing sector of the electronics industry and Huawei products make it easier than ever for customers to connect their products to the cloud. ”

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About HUAWEI M2M Solutions

Huawei Technologies is one of the world's leading providers of information technology and telecommunication solutions. More than one third of the world's population and more than half of the German population directly or indirectly use technology made by Huawei. Headquartered in Shenzhen, the company has 150.000 employees throughout the globe. With its three business units Carrier Network, Enterprise Business and Consumer Business, Huawei Technologies covers 170 countries. Huawei employs 70,000 people in research and development and operates 16 research and development clusters worldwide as well as 28 innovation centres together with partners. For M2M, Huawei offers 3G and 4G embedded modules for automotive, industrial and consumer electronics based on HiSilicon and third-party chipset technology.

About SILICA

SILICA, an Avnet, Inc. (NYSE:AVT) company, is one of the leading semiconductor distributors in Europe. SILICA accelerates its customers' success by connecting 25 technology suppliers with a broad base of more than 15,000 customers and providing in-depth design support and cost-effective, value-added services and solutions. For more information, visit www.silica.com

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